

番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	耐熱ナイロン, UL94V-0 HEAT RESISTANCE NYLON, UL94V-0
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING
③	ネイル NAIL	黄銅 BRASS すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING

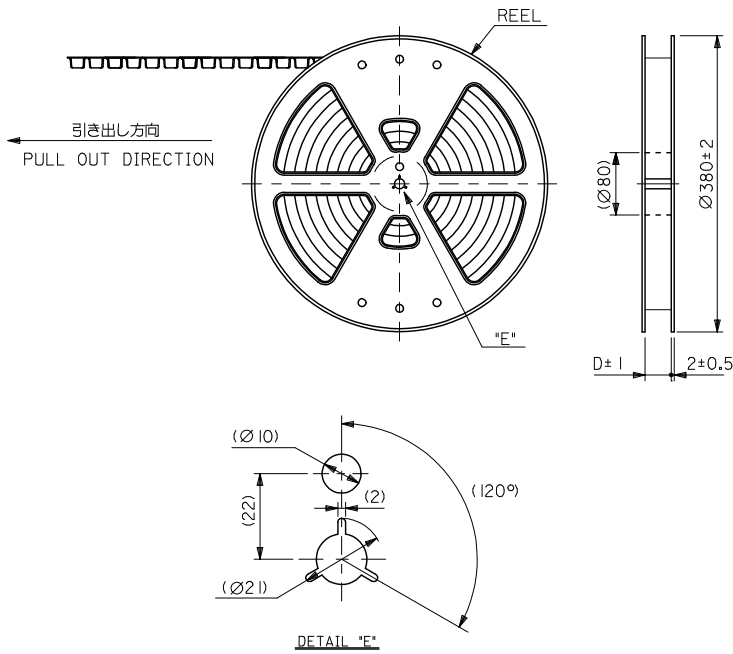
14.0	17.0	15
13.0	16.0	14
12.0	15.0	13
11.0	14.0	12
10.0	13.0	11
9.0	12.0	10
8.0	11.0	9
7.0	10.0	8
6.0	9.0	7
5.0	8.0	6
B	A	極数 CIRCUITS

NOTES

- かん合相手 : 501330-****
MATE WITH : 501330-****
- ソルダーピン及びネイルの平坦度は0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- 極数 = 偶数に適用
APPLY FOR CKT SIZE=EVEN
- 2~5極は, SD-501568-001を参照下さい.
REFER TO SD-501568-001 ABOUT 2-5CKT.
- ELV AND RoHS COMPLIANT.

REVISED EC NO: J2010-0339 DRAWN: NAKAGAWA01 2009/09/01 CHKD: HATAI 2009/09/01 APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY AMIZUMURA	DATE 2005/01/19	TITLE 1.0 WIRE TO BOARD CONN. 1-ROW R/A WAFER ASSY 6-15CKT	
	10 OVER 30 UNDER	± 0.25	CHECKED BY MYAGI	DATE 2005/01/19	MOLEX INCORPORATED	
	30 OVER	± 0.3	APPROVED BY ANODA	DATE 2005/01/19	MATERIAL NO. SEE SHEET 2	DOCUMENT NO. SD-501568-002
ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

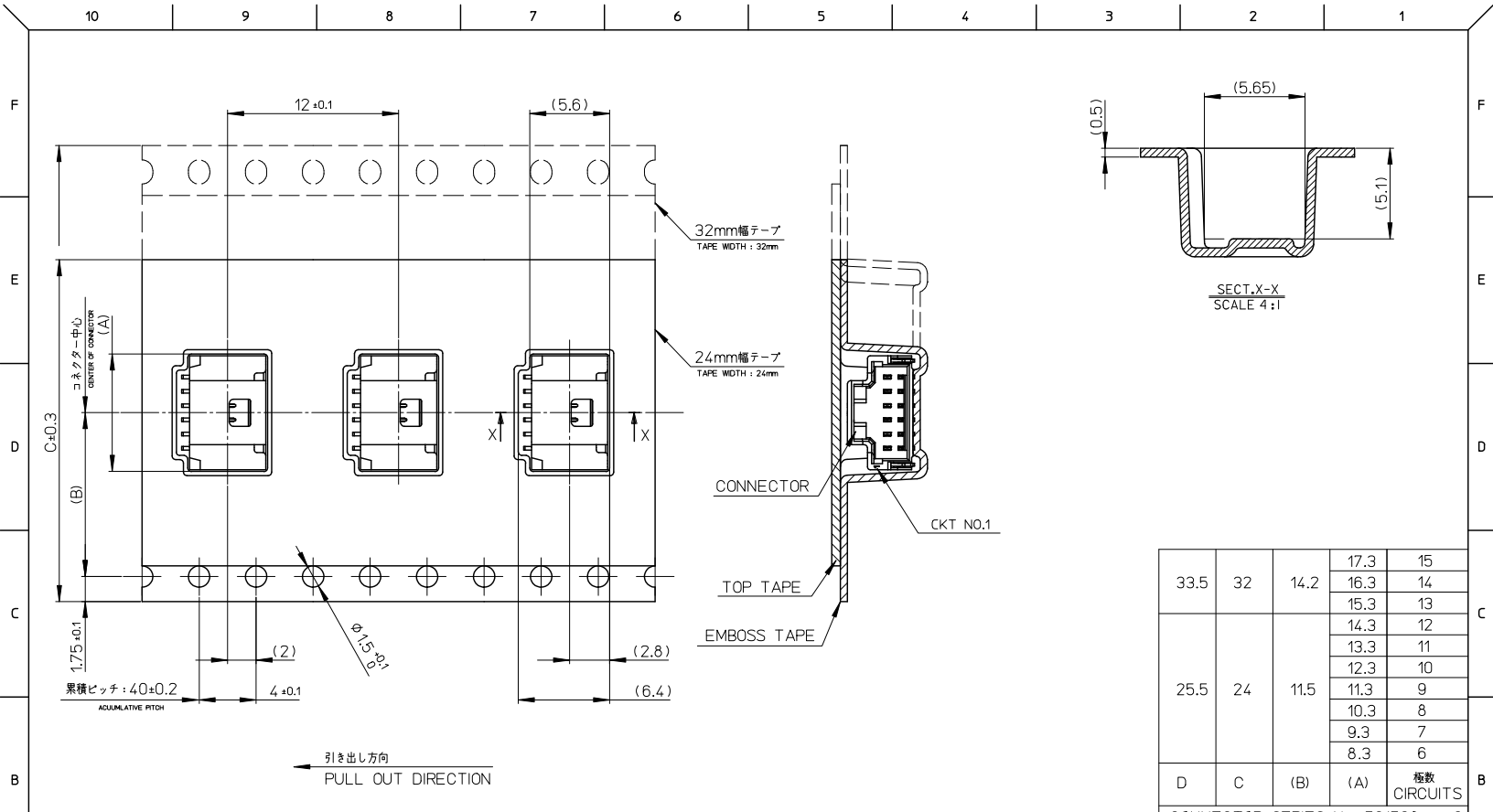
10 9 8 7 6 5 4 3 2 1



NOTES

1. 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
2. 梱包数量: 1300個/リール
NUMBER OF CONNECTORS: 1300 PIECES/REEL
3. リードテープ長さ
LEAD TAPE LENGTH
4. 材料
MATERIAL
キャリアテープ: ポリプロピレン
CARRIER TAPE: POLYPROPYLENE
トップテープ: PET, PE, REF
TOP TAPE
リール: ポリスチレン (リサイクル材を含む)
REEL: POLYSTYRENE (RECYCLE MATERIAL CONTAINED)
5. ELV AND RoHS COMPLIANT.
6. ハイバリア梱包 (シリカゲル入り) 対応品である。(501568-**-07除く)
THIS PRODUCT IS HIGH BARRIER PACKAGE. (WITH SILICAGEL) (BESIDES 501568-**-07)
7. 開梱後の保管条件に注意のこと。(ハイバリア品対象: PS-501568-001参照)
REFER TO PS-501568-001 (HIGH BARRIER PRODUCT) FOR CONDITIONS AFTER OPEN.

REVISED EC NO: J2010-0339 DRAWN: TAKAGAWA01 2009/09/01 CHKD: MATSUOTO 2009/09/01 APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN TAIL METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY AMIZUMURA	DATE 2005/1/26	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTP PKG		
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/1/26	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/1/26	MATERIAL NO. SEE SHEET 3	DOCUMENT NO. SD-501568-006	SHEET NO. 1 OF 3
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



33.5	32	14.2	17.3	15
25.5	24	11.5	16.3	14
			15.3	13
			14.3	12
			13.3	11
			12.3	10
			11.3	9
			10.3	8
			9.3	7
			8.3	6
D	C	(B)	(A)	極数 CIRCUITS

CONNECTOR SERIES No. 501568-***9

REVISED EC NO: J2010-0339 DRAWN: TAKAGAWA01 2009/09/01 CHKD: MATSUJOTO 2009/09/01 APPR: HIRATA 2009/09/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY AMIZUMURA	DATE 2005/1/26	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTP PKG		
	10 OVER 30 UNDER	± 0.25	CHECKED BY MYAGI	DATE 2005/1/26	MOLEX INCORPORATED		
	30 OVER	± 0.3	APPROVED BY ANODA	DATE 2005/1/26	MATERIAL NO. SEE SHEET 3	DOCUMENT NO. SD-501568-006	SHEET NO. 2 OF 3
	ANGULAR ± 3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				


10 9 8 7 6 5 4 3 2 1

紫 VIOLET	橙 ORANGE	茶 BROWN	緑 GREEN	色 COLOR
501568-1597	501568-1587	501568-1577	501568-1567	15
501568-1497	501568-1487	501568-1477	501568-1467	14
501568-1397	501568-1387	501568-1377	501568-1367	13
501568-1297	501568-1287	501568-1277	501568-1267	12
501568-1197	501568-1187	501568-1177	501568-1167	11
501568-1097	501568-1087	501568-1077	501568-1067	10
501568-0997	501568-0987	501568-0977	501568-0967	9
501568-0897	501568-0887	501568-0877	501568-0867	8
501568-0797	501568-0787	501568-0777	501568-0767	7
501568-0697	501568-0687	501568-0677	501568-0667	6
EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUTIS

CONNECTOR SERIES No. 501568-***9

青 BLUE	黄 YELLOW	赤 RED	黒 BLACK	自然色 NATURAL	色 COLOR
501568-1547	501568-1537	501568-1527		501568-1507	15
501568-1447	501568-1437	501568-1427		501568-1407	14
501568-1347	501568-1337	501568-1327		501568-1307	13
501568-1247	501568-1237	501568-1227		501568-1207	12
501568-1147	501568-1137	501568-1127		501568-1107	11
501568-1047	501568-1037	501568-1027		501568-1007	10
501568-0947	501568-0937	501568-0927	501568-0917	501568-0907	9
501568-0847	501568-0837	501568-0827	501568-0817	501568-0807	8
501568-0747	501568-0737	501568-0727		501568-0707	7
501568-0647	501568-0637	501568-0627	501568-0617	501568-0607	6
EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	EMBOSSSED PACKAGE	極数
オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	オーダー番号 ORDER NO.	CIRCUTIS

CONNECTOR SERIES No. 501568-***9

REVISED IEC NO: J2010-0339 DRAWN: NAKAGAWA01 2009/09/01 CHECKED BY: CHYKOHMATSUNO 2009/09/01 APPROVED BY: APRR: HIRATA 2009/09/01 REV:	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY AMIZUMURA	DATE 2005/1/26	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTB PKG		
	10 OVER 30 UNDER	± ---	CHECKED BY MYAGI	DATE 2005/1/26	 MOLEX INCORPORATED DOCUMENT NO. SD-501568-006 SHEET NO. 3 OF 3		
	30 OVER	± ---	APPROVED BY ANODA	DATE 2005/1/26			
ANGULAR ± --- °		MATERIAL NO. SEE TABLE					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					